



SOD118B

hermetically sealed plastic package; axial leaded; 2 leads

8 February 2016

Package information

1. Package summary

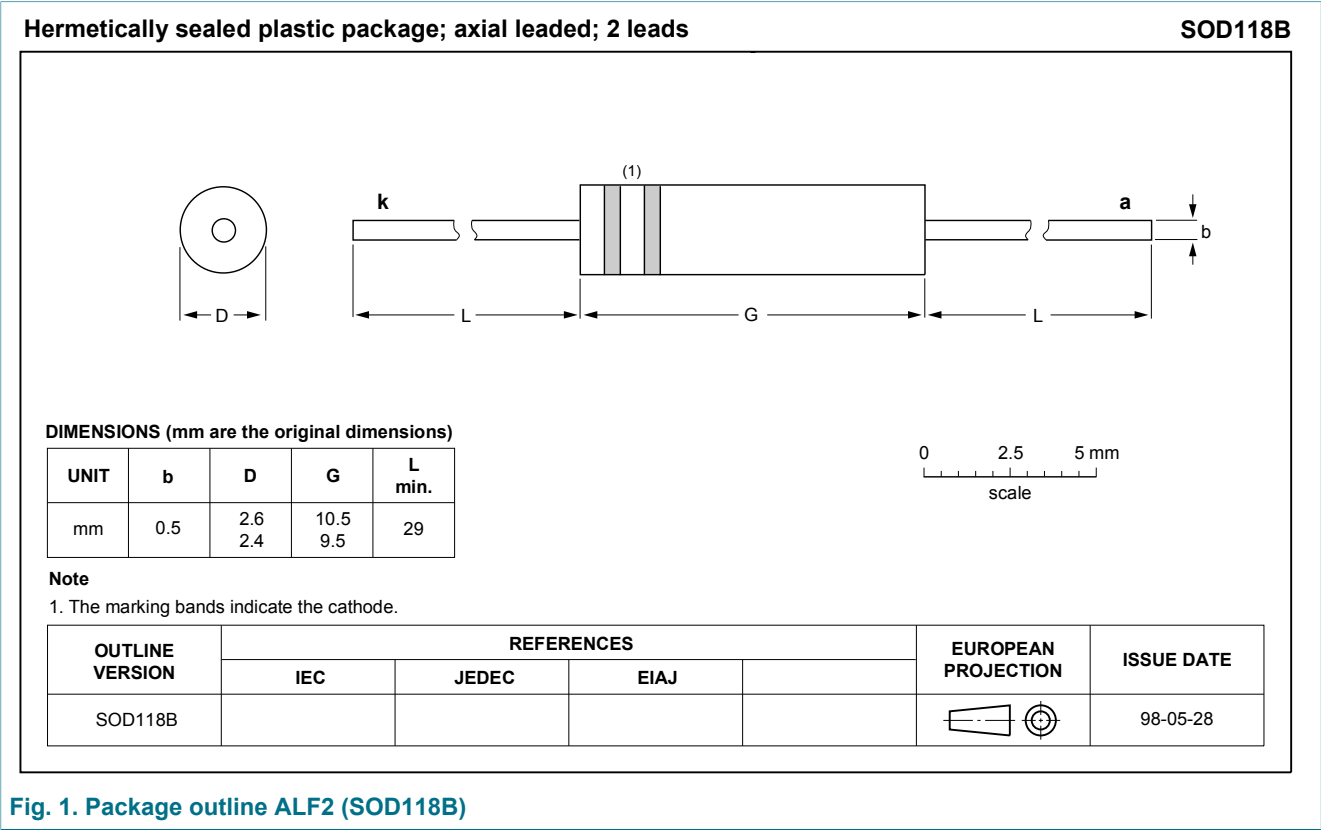
Terminal position code	A (axial)
Package type descriptive code	ALF2
Package type industry code	ALF2
Package style descriptive code	ALF (axial (leaded) long form)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	28-5-1998

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		9.5	-	10	10.5	mm
ΦD	package diameter		2.4	-	2.5	2.6	mm
n_2	actual quantity of termination		-	-	2	-	



2. Package outline



3. Legal information

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